

AMENDMENTS TO THE CLAIMS

Please replace the claims with the following amended claim set:

1. **(Currently amended)** A substrate, comprising:
a transparent base,
a transparent film deposited directly on the transparent base, in which a groove in the deposited transparent film is formed to reach a main surface of said transparent base, and
a wiring portion formed in said groove and in contact with said transparent base,
wherein said groove has a maximum width and a minimum ~~width~~, and width, and said wiring portion in said groove has a width and a thickness determined by correlation with the maximum width and the minimum width of said groove.

2. (Original) The substrate according to claim 1, wherein:
said transparent film is made of a transparent resin.

3. (Original) The substrate according to claim 1, wherein:
said transparent film is made of a photosensitive transparent resin.

4. (Original) The substrate according to claim 1, wherein:
said wiring portion is transparent or opaque.

5. (Original) The substrate according to claim 1, wherein:
said transparent film contains inorganic matter.

6. (Original) The substrate according to claim 1, wherein:

said transparent film is formed using a resin composition comprising an alkali-soluble alicyclic olefin resin and a radiation-sensitive component.

7. (Original) The substrate according to claim 1, wherein:

a surface of said transparent film and a surface of said wiring portion are substantially flush with each other.

8. (Original) The substrate according to claim 1, wherein:

when the maximum width and the minimum width of said groove in transverse section are represented as $W1$ and $W2$, respectively, a maximum wiring width W_i of said wiring portion in said groove has a relationship of $W2 \leq W_i \leq W1$.

9. (Original) The substrate according to claim 8, wherein:

when a thickness of said wiring portion in said groove at the maximum wiring width W_i is represented as t_i , a thickness of said transparent film is represented as $t1$, and a thickness of said transparent film at a position of an average width $((W1+W2)/2)$ of said groove is represented as $t2$, the thickness t_i at a position of said maximum wiring width falls within the range of $t2 \leq t_i \leq t1$.

10. (Original) The substrate according to claim 1, wherein:

said transparent base is made of a glass or a plastic material.

11. (Original) A display device manufactured using said substrate according to claim 1.

12. (Original) The display device according to claim 11, wherein:

said display device is a liquid crystal display device or an EL display device.

13. (Withdrawn) A substrate manufacturing method, comprising the steps of:
- forming a transparent resin film on a surface of a transparent base,
 - selectively removing a surface of said transparent resin film to thereby form a groove reaching said transparent base, and
 - forming a wiring portion in said groove, said wiring portion reaching the surface of said transparent base,
- wherein, in the step of forming said wiring portion, said wiring portion is formed so that a surface of said wiring portion and the surface of said transparent resin film become substantially flush with each other, thereby obtaining a substrate buried with said wiring portion.

14. (Withdrawn) The substrate manufacturing method according to claim 13, further comprising:
- a pretreatment step of treating the surface of said transparent resin film before the step of forming said wiring portion,
- wherein, in said pretreatment step, a wiring formation assistant layer is formed on the surface of said transparent resin film to prevent forming a material of said wiring portion on said wiring formation assistant layer, thereby assisting the formation of the material of said wiring portion in said groove.

15. (Withdrawn) The substrate manufacturing method according to claim 14, wherein:
- said pretreatment step includes the formation of said wiring formation assistant layer on the surface of said transparent resin film, and

said wiring formation assistant layer is selected in relation to the step of forming said wiring portion.

16. (Withdrawn) The substrate manufacturing method according to claim 13, further comprising:

a pretreatment step of forming, on a bottom surface of said groove, a wiring formation assistant layer that serves to assist adhesion of a material of said wiring portion on the surface of said transparent base.

17. (Withdrawn) The substrate manufacturing method according to claim 13, wherein:
said transparent resin film is made of a photosensitive resin composition, and
said photosensitive resin composition comprises a resin selected from the group consisting of an acrylic-based resin, a silicone-based resin, a fluorine-based resin, a polyimide-based resin, a polyolefin-based resin, an alicyclic olefin-based resin, and an epoxy-based resin.

18. (Withdrawn) A substrate manufacturing method, comprising the steps of:
selectively providing a wiring formation assistant layer, which serves as a sacrifice layer, on a surface of a transparent base,
forming a transparent resin film on an exposed surface of said transparent base and said wiring formation assistant layer,
forming a groove in said transparent resin film, and
forming a wiring portion in said groove,
wherein, in the step of forming said wiring portion, said wiring portion is formed so that a surface of said wiring portion and a surface of said photosensitive transparent resin film

become substantially flush with each other, thereby obtaining a substrate buried with said wiring portion.

19. (Withdrawn) The substrate manufacturing method according to claim 13, wherein:
the step of forming said wiring portion is a step of filling said groove with a conductor, which forms said wiring portion.

20. (Withdrawn) The substrate manufacturing method according to claim 14, wherein:
said wiring formation assistant layer is any one of a lift-off layer, a catalyst layer, a water-repellent layer, and an electroless plating assistant layer.

21. (Withdrawn) A method of manufacturing a flat panel display device comprising the step of forming the substrate according to claim 13.

22. (New) The substrate according to claim 1, wherein:
the wiring portion formed in the groove is a single-layer structure.

23. (New) The substrate according to claim 1, wherein:
the wiring portion formed in the groove is a single-layer structure; and
wherein when a thickness of said wiring portion in said groove at the maximum wiring width W_i is represented as t_i , a thickness of said transparent film is represented as t_1 , and a thickness of said transparent film at a position of an average width $((W_1+W_2)/2)$ of said groove is represented as t_2 , the thickness t_i at a position of said maximum wiring width falls within the range of $t_2 \leq t_i \leq t_1$.